

LV-03 BGA rework station picture.



## 2. LV-03 specification..

2.1 Independent three-zone temperature control system

2.2 The upper temperature zone is heated by hot air, while the lower temperature zone is heated by hot air combined with infrared heating. Each of the three temperature zones can be

independently controlled.

2.3 The method of simultaneously heating the upper temperature zone, lower heating zone and IR temperature zone can easily handle lead-free circuit boards, CPU sockets of circuit boards and large BGA chips. The large-area infrared preheating ensures that the PCB will not deform due to temperature differences during disassembly or welding.

2.4 This machine is easy to operate and quick. You can simply place the PCB board on the tray or the tray slot and it will start heating up for use. By moving the upper heating head back and forth and rotating it to any position on the board surface, you can achieve the desired heating effect.

2.5 The upper temperature zone can be manually rotated left or right to move in any direction.

2.6 Using high-precision thermocouples, precise temperature detection is achieved.

2.7 Equipped with various sizes of alloy hot air nozzles, which can rotate 360°, easy to replace, and can be customized according to actual requirements.

2.8 For high-capacity PCBs and other applications with high-temperature requirements, as well as lead-free soldering, it can be handled easily.

2.9 The support plate uses linear bearings for sliding, allowing for precise adjustment of movement.

2.10 A high-power constant-current fan provides infrared cooling for the PCB motherboard, enabling rapid cooling.

### 3. LV-03parameter:

Total power	5100W
Upper heater	1200W
Down heater	1200W
IR heater	2700W (1200W Controllable)
Power	单相(Single Phase) AC 220V±10 50Hz
Location way	V Shape slot+universal jigs
Temperature control	High precision K-type thermocouple (Ksensor) Closed Loop control, independent temperature measurement up and down
Electrical Material	single-chip microcontroller + touch screen

Max PCB size	370×335mm
Min PCB size	20×20mm
Sensor port	1
PCB 厚度	1-5mm
Apply chip	1-50mm
Overall dimension	L470×W485×H490mm
Machine weight	Net weight 28kg